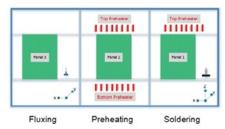
# Integra® Series: Model 508.3

Selective Soldering System in 508.3S, 508.3PD or 508.3PD 2seg Configurations



The Integra® 508.3 is a multi-station selective soldering system designed for high-volume applications with maximum throughput. With its highly flexible configuration, the Integra® 508.3 allows soldering of printed circuit boards as large as 508 x 508 mm (20.0 x 20.0 in.).

**Versatility.** Customers can choose between three different variants of the Integra® 508.3 to meet a broad range of selective soldering requirements. The Integra® 508.3S configuration with single fluxer and solder pot provides single board processing.



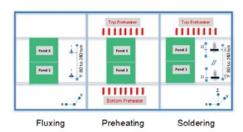
Integra® 508.3S configuration

The Integra® 508.3PD configuration with dual drop-jet fluxers and dual solder pots allows for using two solder nozzles in the same soldering station or processing two boards in a panel simultaneously. The Integra® 508.3PD is capable of processing up to 6 boards at one time. Parallel processing enables fluxing and soldering of two printed circuit boards at the same time doubling machine productivity. The Integra® 508.3PD 2seg configuration with dual fluxers and solder pots can solder two

#### **Features and Benefits**

- Three-zone operation with concurrent fluxing, preheating and soldering for increased throughput with maximum preheat capabilities
- Choice of single or dual drop-jet fluxers and solder pots for either simultaneous parallel or independent double processing modes
- Parallel processing significantly increases machine through put while double processing broadens soldering flexibility
- 2segment configuration can solder two boards in-line with two segmented conveyors without boards being panelized or requiring tooling
- Full titanium solder pots compatible with all solder alloys plus easy tool-free maintenance

singulated boards in a parallel mode in-line with two segmented conveyors. This allows sequential soldering of two printed circuit boards at the same time without the need for the boards to be in a panel, to be palletized or to require tooling.



Integra® 508.3PD configuration

**Value.** With a reputation for innovation, comprehensive process solutions from Nordson SELECT ensure a maximum return on investment and low cost of ownership. From initial process development through full-scale production, you are supported by our experienced worldwide engineering, applications development and technical service network.



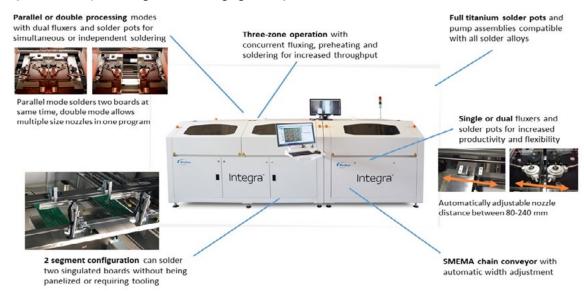
# Integra® Series: Model 508.3

Selective Soldering System in 508.3S, 508.3PD or 508.3PD 2seg Configurations

# Integra® 508.3 Features

The Integra® 508.3 is a fully configured SMEMA compatible selective soldering platform and is a reliable and cost-effective solution for many demanding through-hole and SMT mixed-technology soldering applications including:

- Double-sided TH/SMT assemblies
- TH selective and mini-wave soldering
- Multiple solder alloy soldering without changing solder pot



#### **Standard Features**

Three-zone operation with independent zones for concurrent fluxing and preheating plus single selective soldering station (508.3S)

SMEMA chain conveyor with positive PCB location Automatic conveyor width adjustment

MicroDrop drop-jet fluxer

Flux level sensing system

Full surface bottom-side infrared preheating

All titanium solder pot and pump assembly

Quick change magnetically coupled solder nozzle

Automatic solder pot level monitoring

Automatic wave height monitoring

Heated nitrogen inerting system

Process viewing camera

PhotoScan editor and machine control software

- Easy "point-and-click" programming
- Remote machine control
- Remote machine maintenance
- Network and FIS capability

TFT monitor

## **Additional Configurations**

Dual MicroDrop drop-jet fluxers and dual solder pots for parallel or double soldering modes (508.3PD)

Dual MicroDrop drop-jet fluxers and dual solder pots for parallel or double soldering modes or sequential soldering of two boards in-line (508.3PD 2seg)

### **Optional Features**

Fully-automated fiducial alignment and board mapping In-process, closed-loop flux verification system for drop-jet control

Full surface topside infrared preheating

Full surface bottom-side infrared preheating

Closed-loop pyrometer control

Board warpage sensing system

Dual process viewing camera and second monitor

Automatic solder wire feeding system

Automatic solder level sensing system

Wave height control sensing system

AOI solder joint inspection system

Automatic solder nozzle cleaning system

Data logging system with traceability of all process parameters, barcode reader



# Integra <sup>®</sup> Series: Model 508.3

# **Specifications**

## **Motion System**

 $\begin{array}{lll} Z \ accuracy & \pm 100 \ \mu m \ (0.004 \ in.) \\ Z \ repeatability \ ^{(1)} : & \pm 50 \ \mu m \ (0.002 \ in.), \ 3 \ sigma \\ Z \ velocity : & 0.05 \ m/s \ peak \ (2 \ in./s) \\ X-Y \ accuracy & \pm 100 \ \mu m \ (0.004 \ in.) \\ X-Y \ repeatability \ ^{(1)} : & \pm 50 \ \mu m \ (0.002 \ in.), \ 3 \ sigma \\ X-Y \ velocity : & 0.2 \ m/s \ peak \ (8 \ in./s) \\ \end{array}$ 

#### Computer

PC with Windows® operating system

#### **Software**

PhotoScan "point-and-click" programming editor and machine control software

# **Solder Pot Capacity and Weight**

Capacity (2): Approx. 12.0 kg (26.4 lbs.)

Total weight of tin-lead solder together with solder pot

and pump assembly (2): Approx. 22.4 kg (49.2 lbs.)

Total weight of lead-free solder together with solder pot and

pump assembly (2): Approx. 19.7 kg (43.3 lbs.)

Max. temperature: 320°C

#### Solderable Area (X-Y)

Single, parallel or double operating mode  $^{(3,4)}$ : Max. 508 x 508 mm (20.0 x 20.0 in.) Min. 50 x 50 mm (2.0 x 2.0 in.)

### **Preheating**

Selectable topside preheating from 1.5 kW to 12.0 kW Selectable bottom preheating from 1.5 kW to 6.0 kW

#### **Board Handling Capability**

508.3S and 508.3PD (3, 4):

Max. board size: 508 x 508 mm (20.0 x 20.0 in.) Min. board size: 50 x 50 mm (2.0 x 2.0 in.)

508.3PD 2seg (3, 4):

Transport height (6):

Max. board size: 350 x 508 mm (13.8 x 20.0 in.) Min. board size: 50 x 50 mm (2.0 x 2.0 in.)

#### Conveyor

Max. board/carrier length: 508 mm (20.0 in.)

Min. board/carrier width: 508 mm (20.0 in.)

Max. board/carrier width: 508 mm (20.0 in.)

Min. board/carrier width: 50 mm (20.0 in.)

Max. board/carrier thickness: 50 mm (20.0 in.)

Max. board/carrier thickness: 15.2 mm (0.6 in.)

Max. overboard clearance: 120 mm (4.7 in.)

Max. underboard clearance: 40 mm (1.5 in.)

Edge clearance (5): 3 mm (0.12 in.), edge conveyor

including on-rail clamps Conforms to SMEMA standard for conveyor height;

height adjustable from 940-965 mm (37.0 - 38.0 in.) from floor

to bottom of board

Load capacity (7): 7.5 kg (16.5 lbs.)

Operation modes: Automatic (SMEMA), manual or pass-through

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#### **Facilities Requirements**

 System footprint:

 508.3S/508.3PD
 3350 x 1700 mm (131.9 x 66.9 in.)

 508.3PD 2seg
 4500 x 1700 mm (177.2 x 66.9 in.)

 Compressed air:
 6 bar (90 psi) min., 8 bar (110 psi) max.

Power (mains) (8):

508.3S 400/480VAC, 50-60 Hz, three phase, 23

kW, 33 A without preheating, or 29 kW,

42 A with preheating

508.3PD 400/480VAC, 50-60 Hz, three phase, 26

kW, 38 A without preheating, or 32 kW,

46 A with preheating

508.3PD 2seg 400/480VAC, 50-60 Hz, three phase, 29

kW, 42 A without preheating, or 36 kW,

50 A with preheating

Nitrogen: 99.99% (4.0) pure, 4-6 bar (60-90 psi),

1.3 m<sup>3</sup>/hour (single pot), 2.6 m<sup>3</sup>/hour

(dual pot)

Ventilation: 300 m<sup>3</sup>/hour (180 SCFM), two 100 mm

(4.0 in.) dia. Ducts

System weight (9, 10): 1500 kg (3300 lbs.)

(1) Repeatability is measured at full rated system speed.

(2) Solder capacity and total weight of solder pot and pump assembly varies depending on solder alloy.

(3) Board size is reduced when operating in parallel or double modes and 2 segment sequential mode

(4) Contact factory regarding smaller or larger boards/carriers.

(5) Edge conveyor conforms to SMEMA standards.

(6) 900 mm (35.4 in.) non-SMEMA conveyor height available upon request.

(7) Total weight of all parts on conveyor at any one time. Contact factory regarding requirements for greater load capacity.

(8) Electrical power varies depending on configuration.(9) System weight varies depending on configuration.

(10) Configuration dependent. Other configurations may be available. Contact Nordson SELECT.

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#### **Standards Compliance**

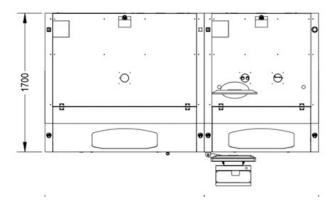
SMEMA, CE

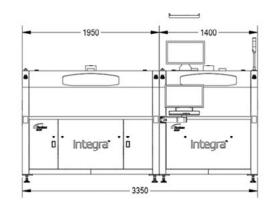
Additional options may be available: contact Nordson SELECT for further information.

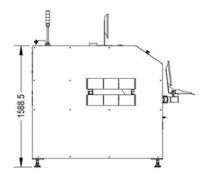


# Integra <sup>®</sup> Series: Model 508.3S and PD

# **Dimensions are in Millimeters**







For more information speak with your local sales rep or contact your regional office.

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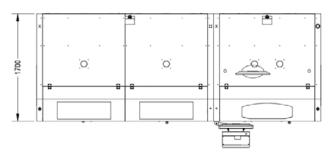
+886.229.02.1860 Phone

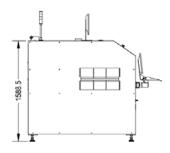
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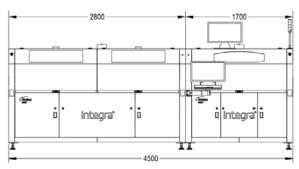


# Cerno ® Series: Model 508.3PD 2seg

## **Dimensions are in Millimeters**

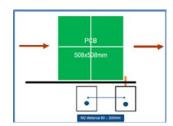




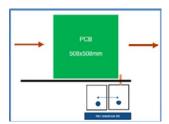




Integra® 508.3PD 2seg soldering two singulated boards in parallel mode



Integra® 508.3PD 2seg soldering one panelized board with dual nozzles



Integra® 508.3PD 2seg soldering one board with small and large nozzles

For more information speak with your local sales rep or contact your regional office.

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